













- ► Subminiature SMD
- ➤ 2520 Series
- ► Green (525nm)

N0G08S22







Subminiature 2520

APPLICATIONS:

- Backlighting
- Indication Light
- Switch light
- Dashboard

2520 Series





FEATURES:

Package: Subminiature SMD Forward Current: 20mA

Forward Voltage (typ.): 3.7V

Luminous Intensity (typ.): 1800mcd @20mA

Colour: Green

Wavelength: 525nm Viewing angle: 20°

Materials:

Die: InGaN

Resin: Epoxy (Water Clear)

Operating Temperature: -20~+80°C

Storage Temperature: -30~+100°C

ESD: 150V

Grouping parameters:

Forward voltage

Luminous intensity

Dominant Wavelength

Soldering methods: Reflow

Preconditioning: acc. to JEDEC Level 3

Packing: 12mm tape with 1500/reel, ø180mm (7")



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I _F	30	mA
Peak Forward Current Duty 1/10@10KHz	I _{FP}	100	mA
Reverse Current @5V	I _R	50	μΑ
Power Dissipation	PD	120	mW
Electrostatic Discharge	ESD	150	V
Operating Temperature	T _{OPR}	-20~+80	°C
Storage Temperature	T _{STG}	-30~+100	°C

Electrical & Optical Characteristics (Ta=25°C)

Darameter	Cumbal	Values			Unit	Test
Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Forward Voltage	V_{F}	3.5		4.0	V	I _F =20mA
Luminous Intensity	I _V	1100	1800		mcd	I _F =20mA
Dominant Wavelength	λ_{D}		525		nm	I _F =20mA
Spectral Line Half Bandwidth	Δλ		36		nm	I _F =20mA
Viewing Angle	2θ _{1/2}		20		deg	I _F =20mA

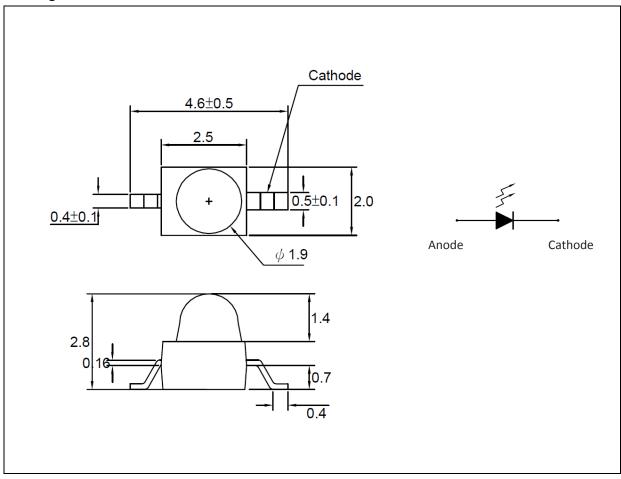
^{1.} Luminous intensity (I_V) ±15%, Forward Voltage (V_F) ±0.1V, Viewing angle(2 $\theta_{1/2}$) ±5%

^{2.} IS standard testing



OUTLINE DIMENSION:

Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.



BINNING GROUPS:

Forward Voltage Classifications ($I_F = 20mA$):

Code	Min.	Max.	Unit
1	3.4	3.5	
2	3.5	3.6	
3	3.6	3.7	V
4	3.7	3.9	V
5	3.9	3.9	
6	3.9	4.0	

Luminous Intensity Classifications ($I_F = 20$ mA):

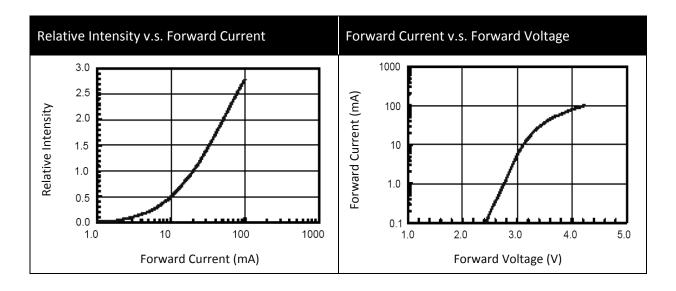
Code	Min. Max.		Unit
G1	1100	1300	
G2	1300	1500	
G3	1500	1700	mad
G4	1700	1900	mcd
G5	1900	2100	
G6	2100	2300	

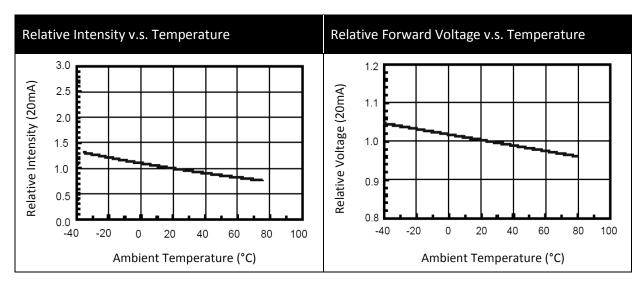
Dominant Wavelength Classifications ($I_F = 20$ mA):

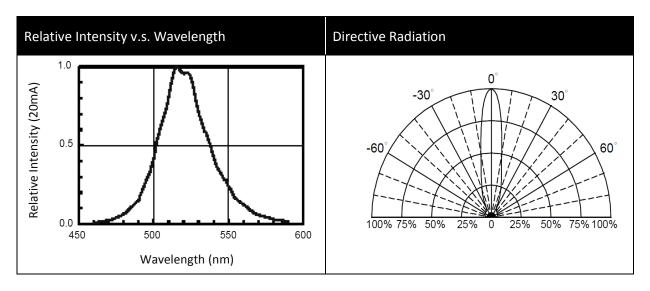
Code	Min. Max.		Unit
36	515	520	
37	520	525	
38	525	530	nm
39	530	535	



ELECTRO-OPTICAL CHARACTERISTICS:





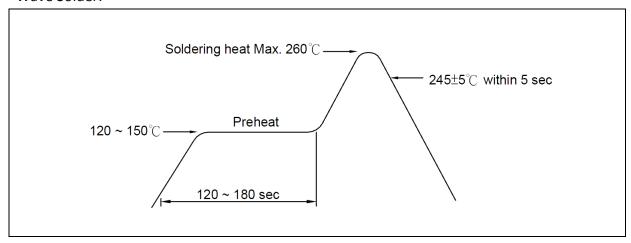


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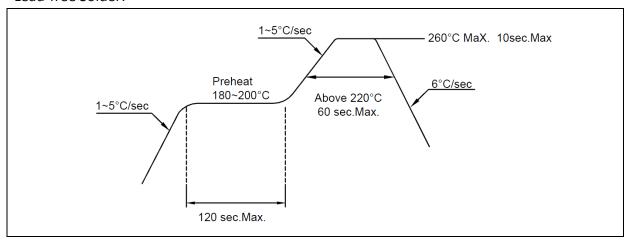


RECOMMENDED SOLDERING PROFILE:

Wave Solder:



Lead-free Solder:



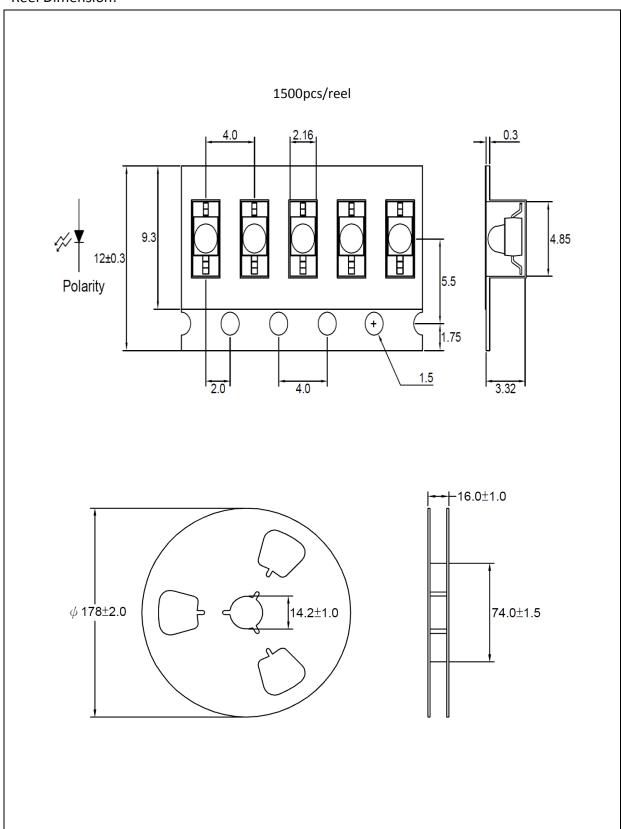
Note:

- 1. Maximum reflow soldering: 2 times.
- 2. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:

Reel Dimension:





PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 month at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent and apply baking at 60°C±5°C for 15hrs before use.

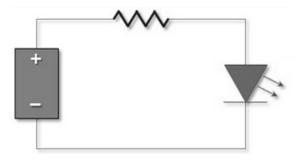
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 70±3°C x 24hrs and <5%RH, taped / reel package.
- 100±3°C x 2hrs, bulk (loose) package.
- 130±3°C x 30min, bulk (loose) package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

Version	Date	Summary of Revision
A1.0	15/04/2014	Datasheet set-up.
A1.1	16/07/2014	P/N change from N0G08L16 to N0G08L22.
A1.2	13/11/2015	Part number change.